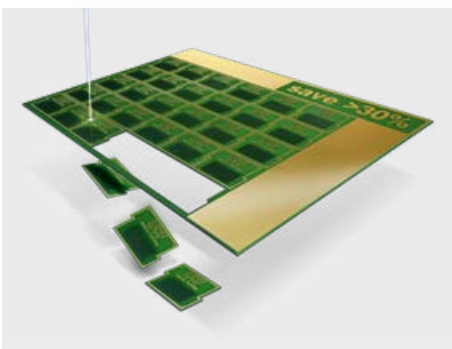
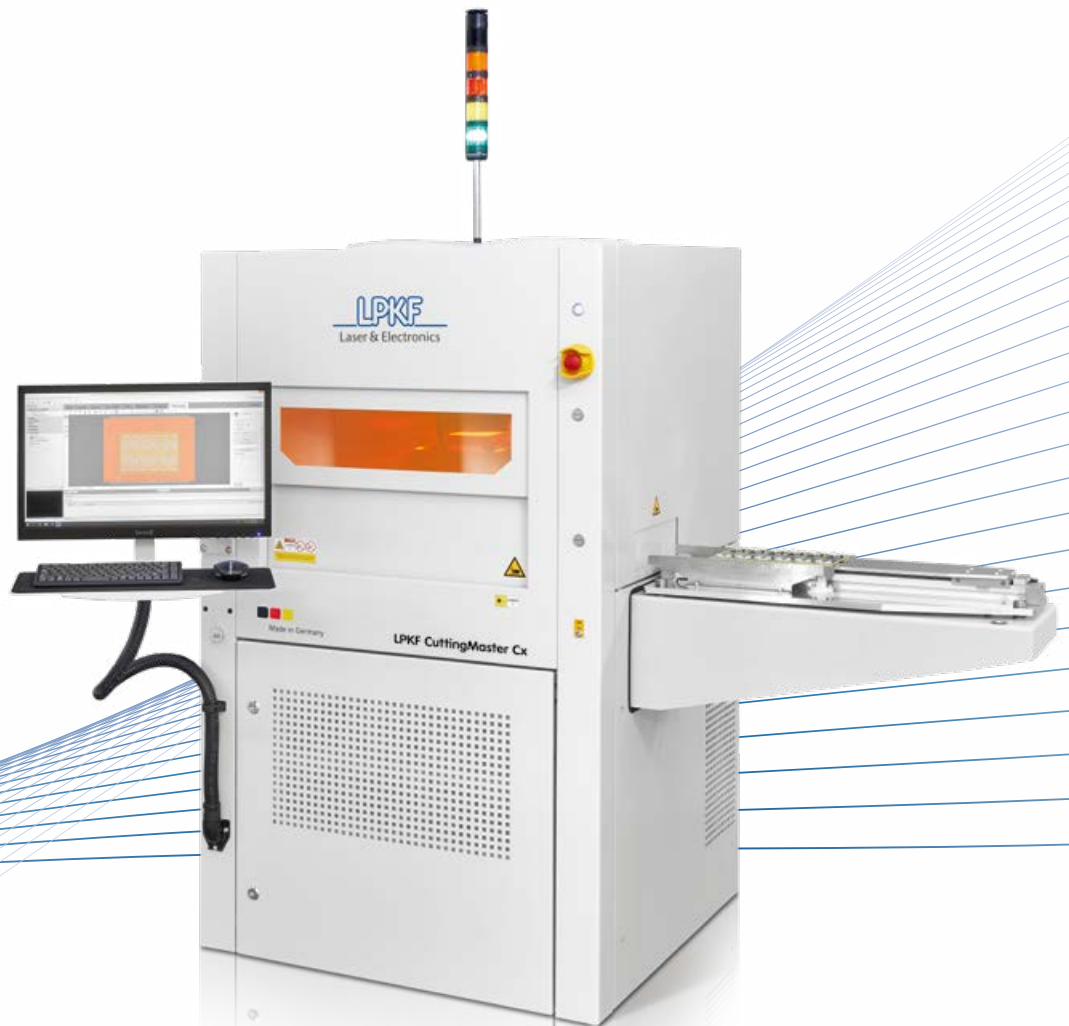


# Highly Automated Laser Depaneling for Maximum Use of Potential

## LPKF CuttingMaster 2000 Cx

- Economic and reliable PCB depaneling
- Compact and cost-efficient automation solution
- Saving revolving workpiece carriers
- Easy integration in production lines



# Cost-Effective Automation for Laser Depaneling – LPKF CuttingMaster 2000 Cx

Laser depaneling at its best: Consistent system optimizations for even more cost-effectiveness. The LPKF CuttingMaster 2000 Cx is especially designed for large quantities of rigid PCB depaneling. It works stand-alone or integrated into production lines. The CuttingMaster Cx system comes with a new automation solution that makes special workpiece carriers redundant.

## Cost-Effective Automation Solution

The sophisticated functionality and compact design of the CuttingMaster Cx make it a highly cost-effective and attractive automated laser depaneling solution. It uses an integrated clamping device and a product-specific fork for holding and unloading. This makes revolving workpiece carriers redundant.

## Flexible Automation

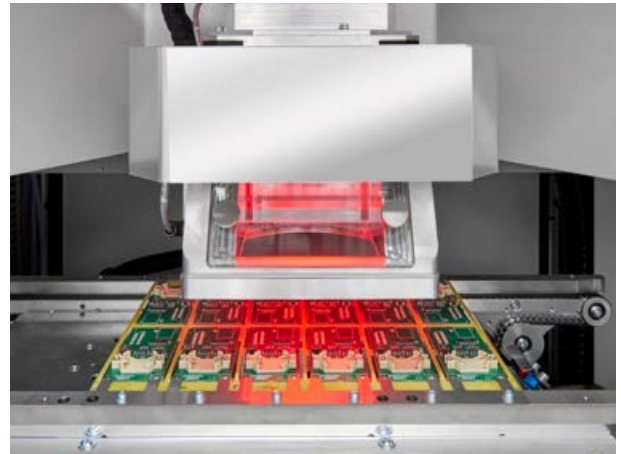
Additionally for example a robotic arm can be installed to unload the separated PCBs and remaining frame. Thanks to the SMEMA and OPC UA interfaces further third-party-automation solutions can be supplemented flexibly. Integration into the process setup is quick and easy.

## High-Level Software LPKF CircuitPro

The intuitive LPKF CircuitPro system software generates optimal process data from the layout data. This ensures the best possible cutting quality and performance. In a very short time, existing applications can be adapted or new projects can be created in this way.

## Extending the High Performance

Through the clever and reliable hardware, the easy-to-use software and the integration of standardized interfaces, the CuttingMaster Cx improves high performance of the 2000 series. It uses a powerful laser source and sophisticated Tensor Technology for PCB depaneling of full contours or tab cuts.



LPKF CuttingMaster 2000 Cx	
Max. working area (X x Y)	350 mm x 250 mm
Positioning accuracy	± 25 µm
Diameter of focused laser beam	~20 µm
System dimensions (W x H x D)	1600 mm x 2180 mm x 1140 mm*
Weight	~ 500 kg
Optional features	OPC UA standard interface, advanced exhaust head, uninterruptable power supply

Laser power	Wavelength	Pulse duration	System variant
40 W	532 nm	Nanosecond	2240

\* Height incl. status light

